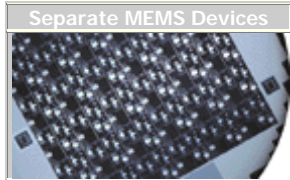




## Dry Process Dicing™ vs. Sawing



In comparing sawing with scribe and break technologies, the scribe and break method can process wafers faster than sawing without any residual stress or the use of cooling water. Since the Dry Process Scriber/Breaker requires no de-ionized water for the separation process, there are no damaging swarf particles in the water, no post process cleaning, and no water disposal. The scribe speed is not affected by wafer thickness or die size.

Once each street is scribed with Dynatex International's precision diamond scribe tool, the breaking mechanism delivers an exact impact directly below the scribe line, cleanly separating the die.